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(12) **United States Design Patent**
Muramoto

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(54) **LIGHT-EMITTING DIODE CHIP**

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(72) Inventor: **Eiji Muramoto**, Kanazawa (JP)

(73) Assignee: **Kabushiki Kaisha Toshiba**, Tokyo (JP)

(**) Term: **14 Years**

(21) Appl. No.: **29/473,952**

(22) Filed: **Nov. 27, 2013**

(30) **Foreign Application Priority Data**

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May 30, 2013 (JP) 2013-012007

(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/180**

(58) **Field of Classification Search**
CPC ... H01L 25/167; H01L 25/0753; H01L 27/15; H01L 27/156; H01L 31/02; H01L 33/00; H01L 33/04; H01L 33/08; H01L 33/10; H01L 33/20; H01L 33/38; H01L 33/42; H01L 33/483; H01L 33/486
USPC D13/180; D26/1; 257/79, 80, 81, 88, 257/89, 95, 98, 99, 100, E33.058; 313/483, 313/498, 500; 362/249.01, 49.02, 555
See application file for complete search history.

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Primary Examiner — Selina Sikder
(74) *Attorney, Agent, or Firm* — Banner & Witcoff, Ltd.

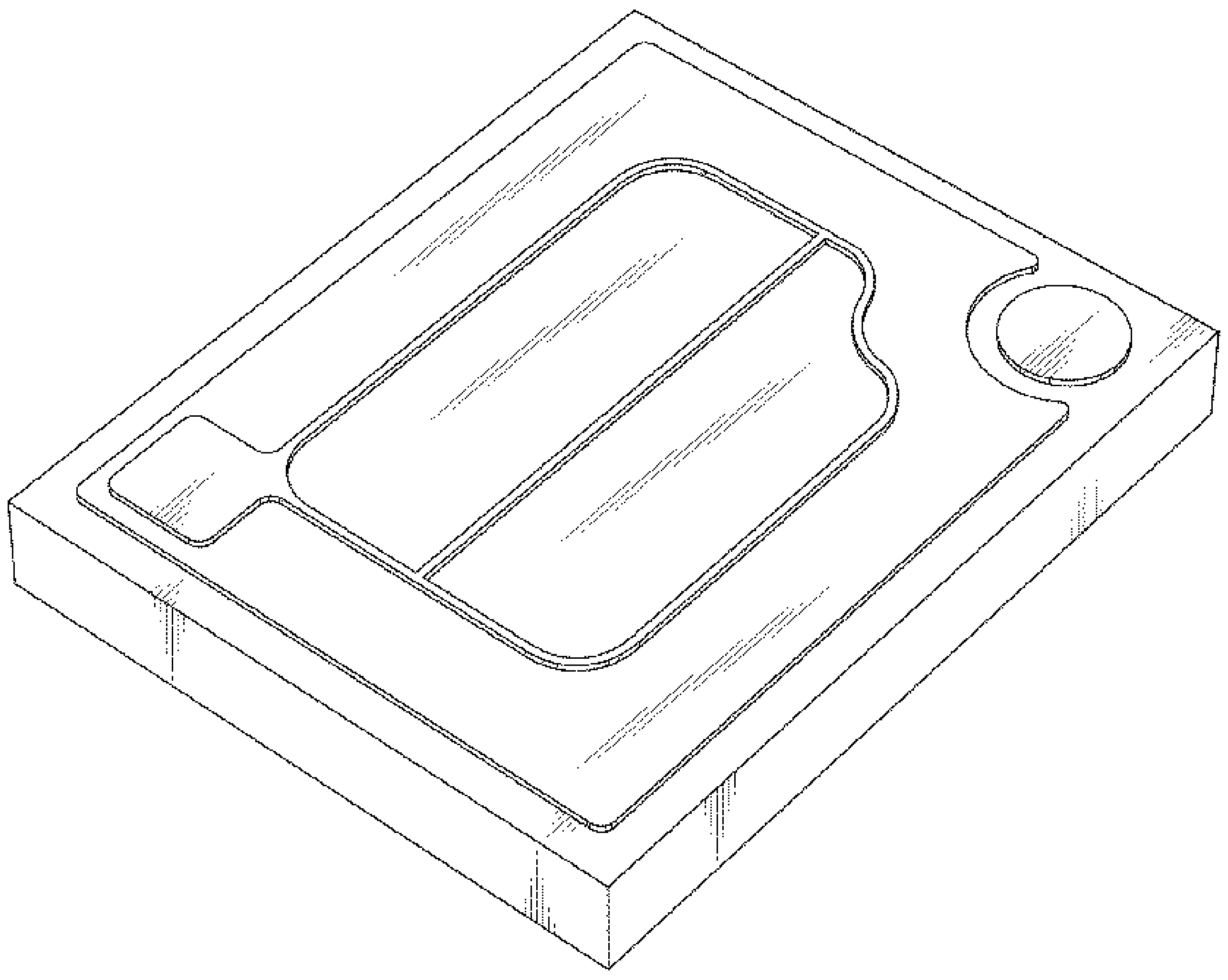
(57) **CLAIM**

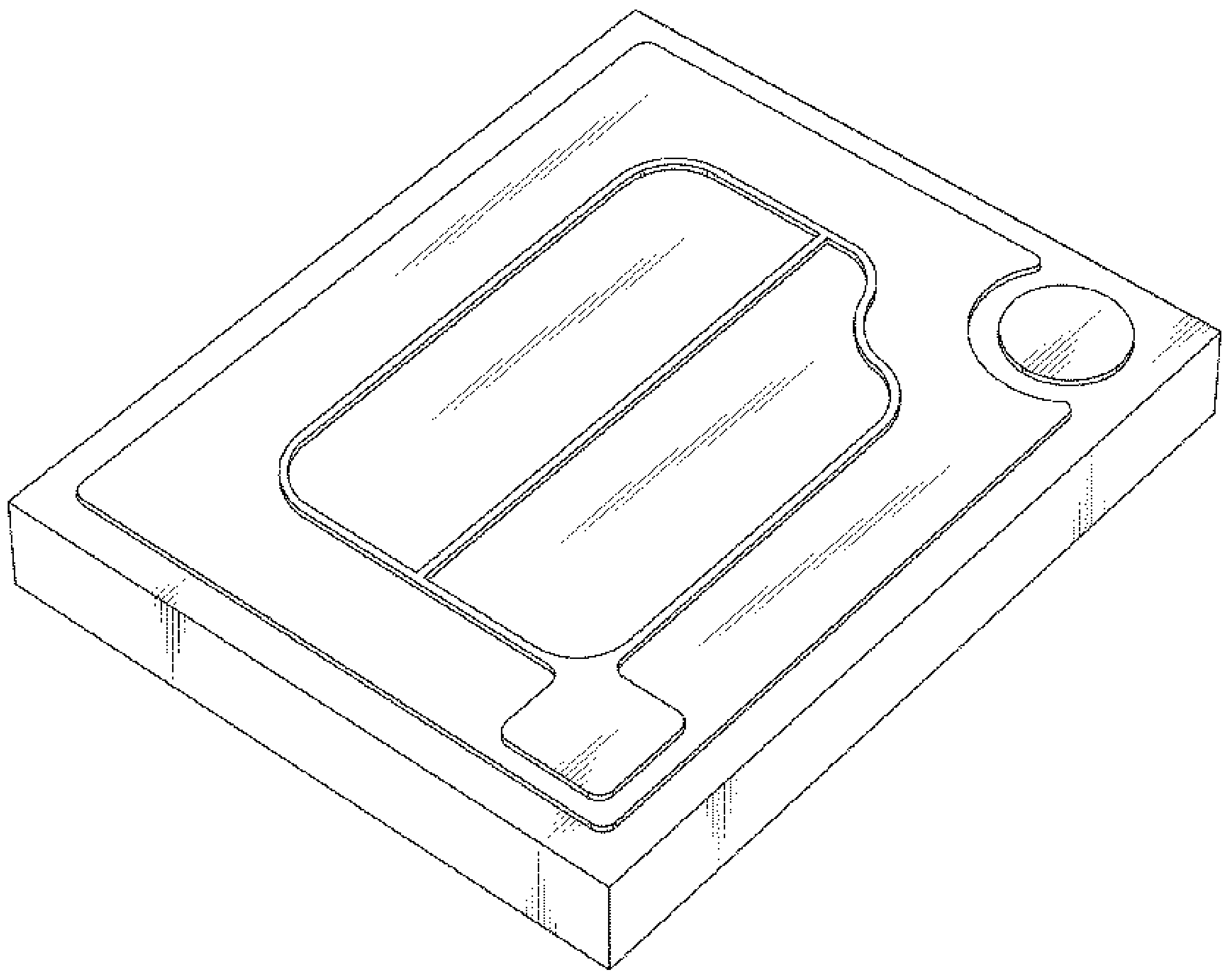
The ornamental design for a light-emitting diode chip, as shown and described.

DESCRIPTION

FIG. **1** is a front, bottom and right side perspective view of a light-emitting diode chip, showing my new design;
FIG. **2** is a front view thereof;
FIG. **3** is a top view thereof;
FIG. **4** is a left side view thereof;
FIG. **5** is a right side view thereof;
FIG. **6** is a bottom view thereof;
FIG. **7** is a rear view thereof;
FIG. **8** is a front, bottom and right side perspective view of a second embodiment of the light-emitting diode chip, showing my new design;
FIG. **9** is a front view thereof;
FIG. **10** is a top view thereof;
FIG. **11** is a left side view thereof;
FIG. **12** is a right side view thereof;
FIG. **13** is a bottom view thereof; and,
FIG. **14** is a rear view thereof.

1 Claim, 8 Drawing Sheets





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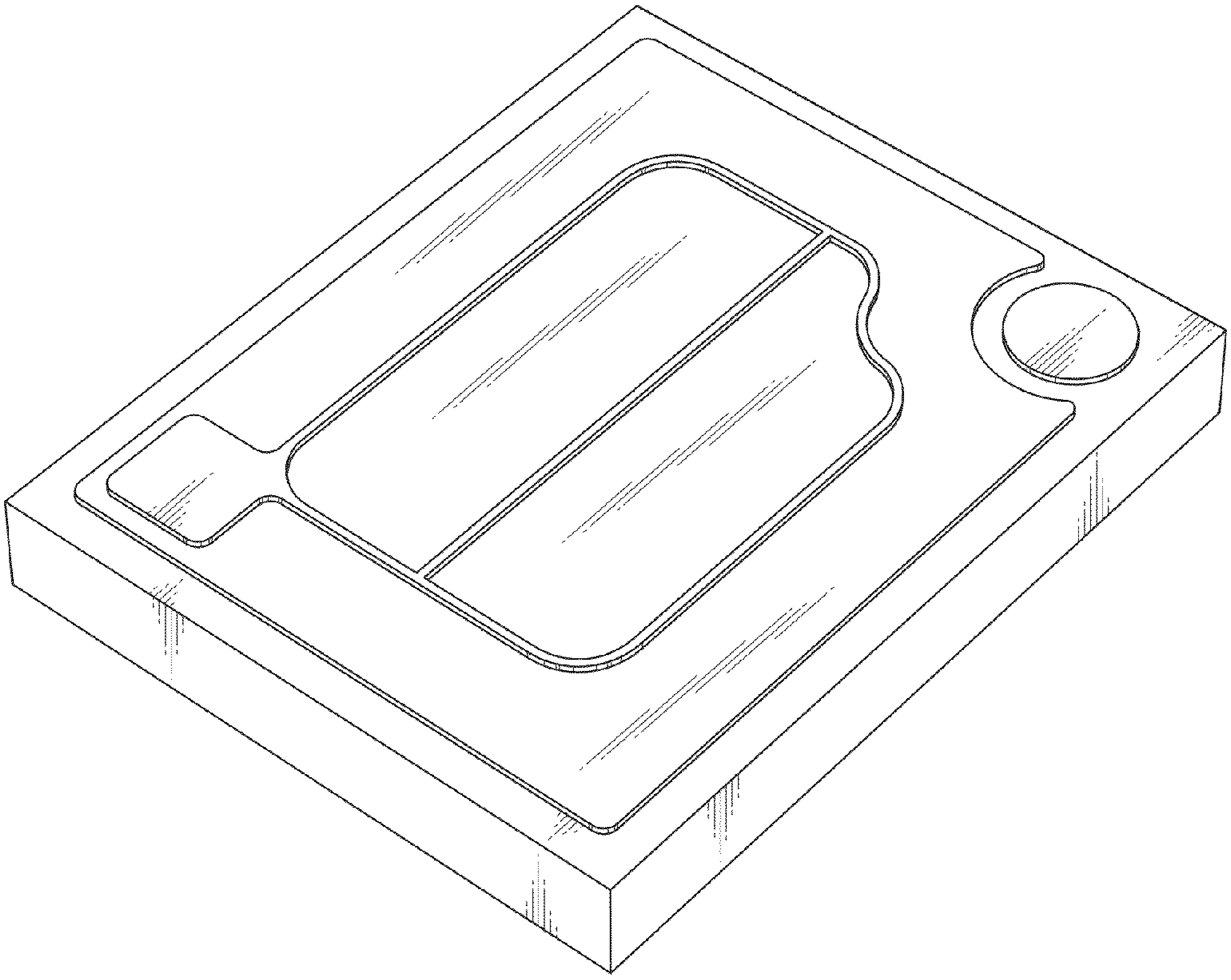

FIG. 1

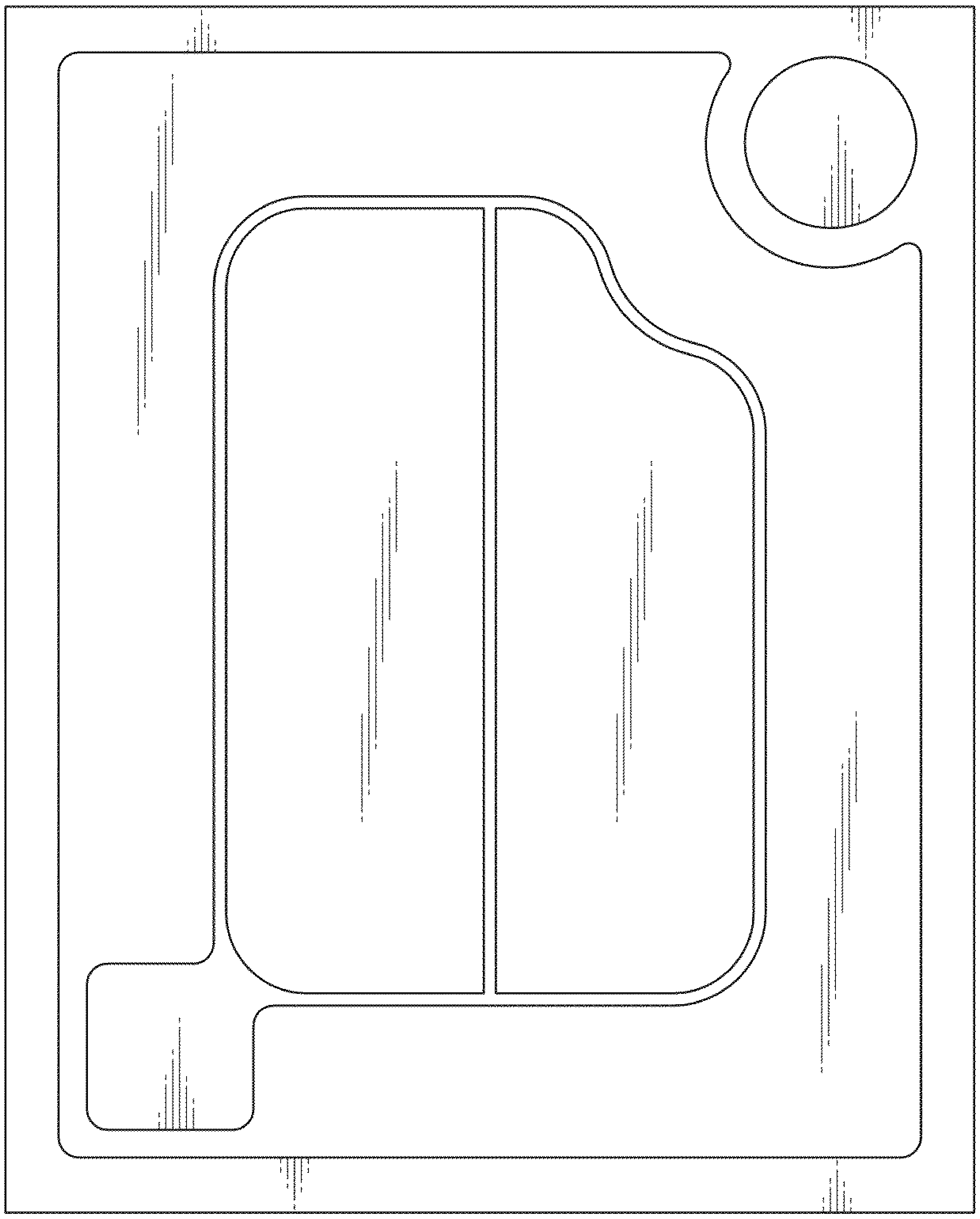

FIG. 2

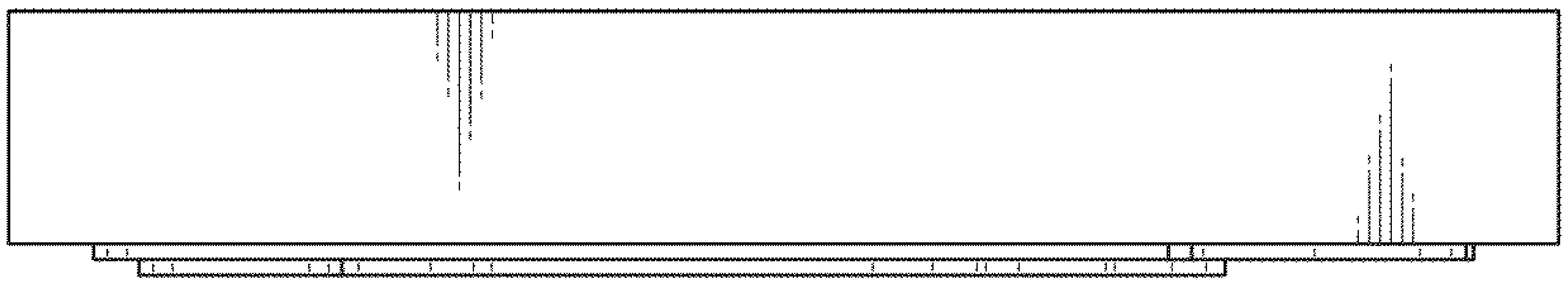

FIG. 3

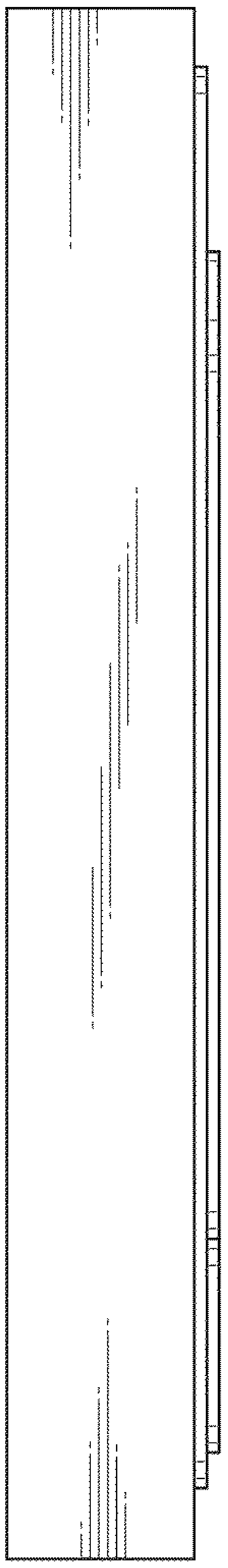

FIG. 4

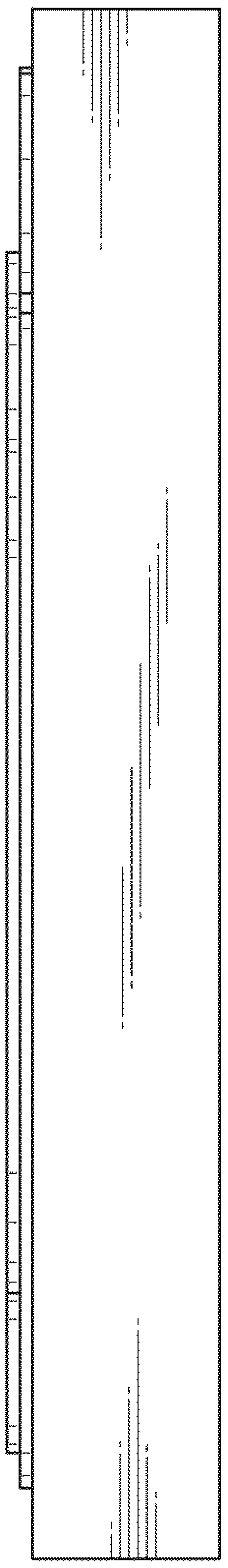

FIG. 5

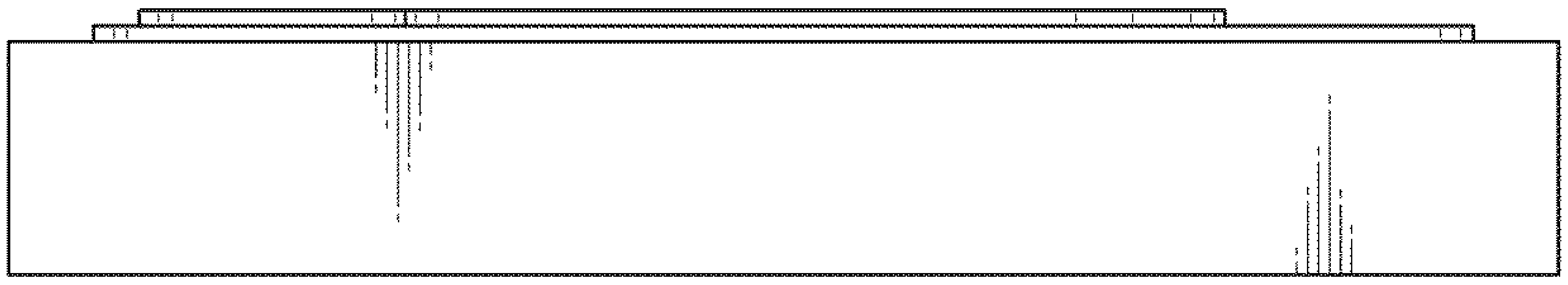

FIG. 6

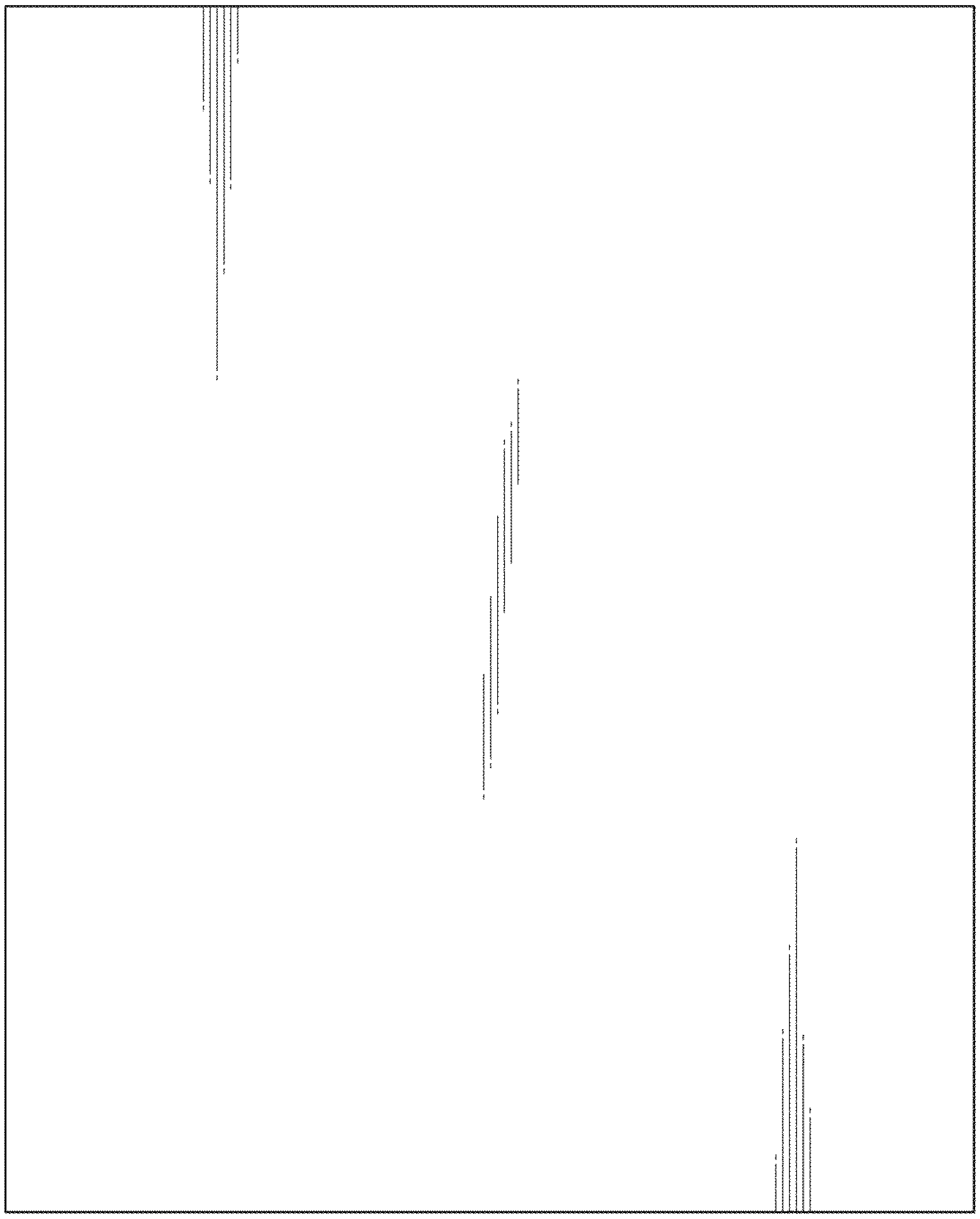

FIG. 7

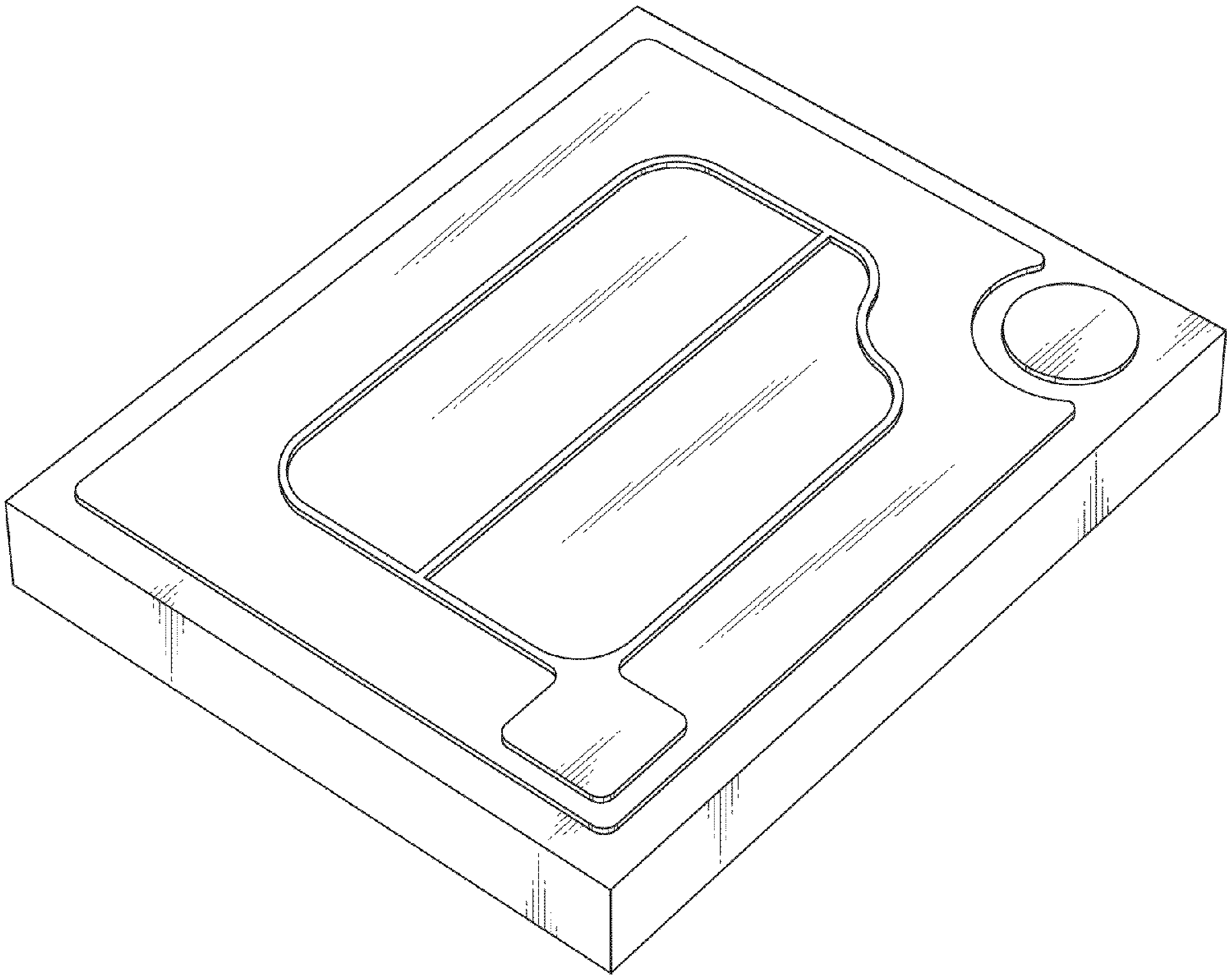

FIG. 8

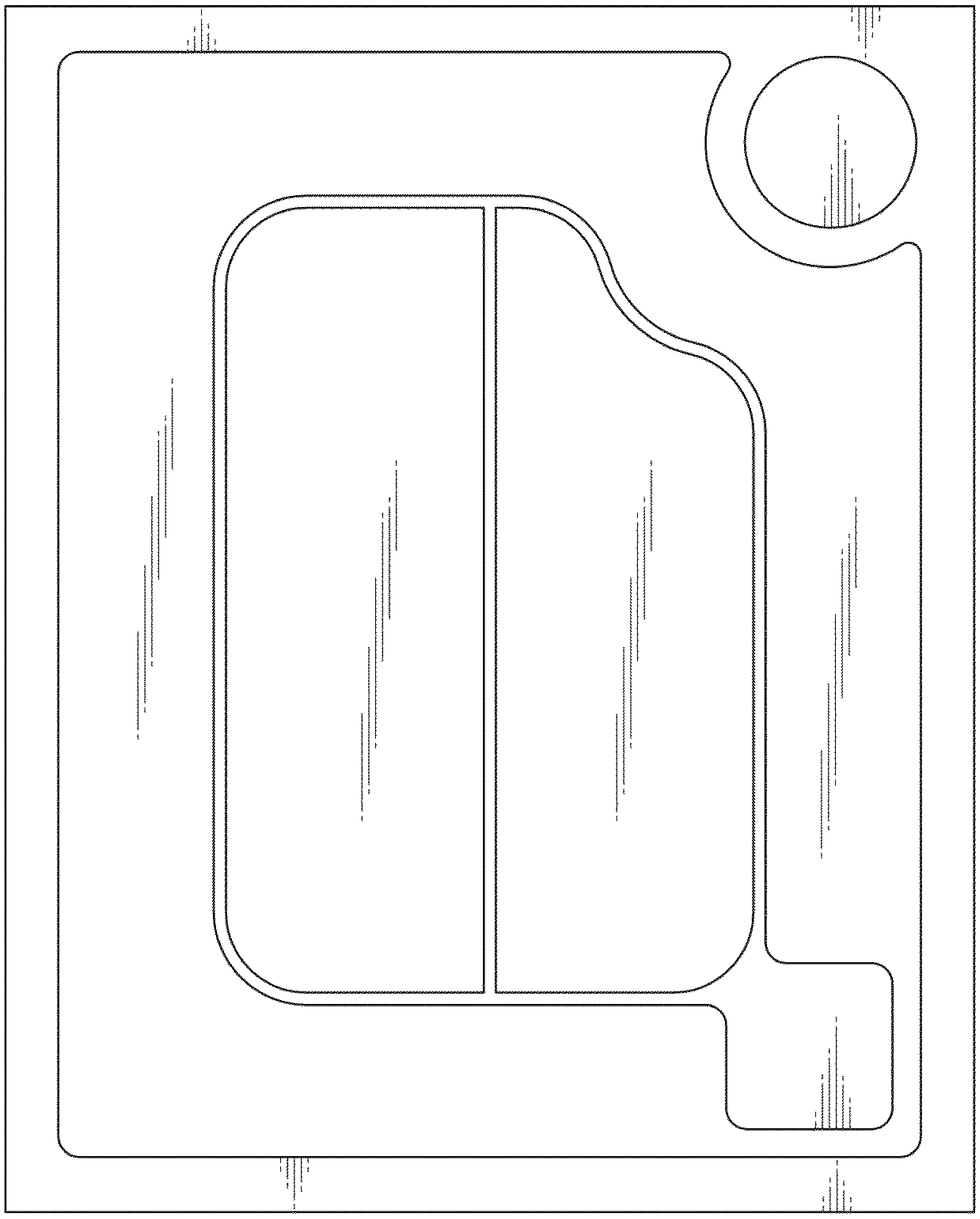

FIG. 9

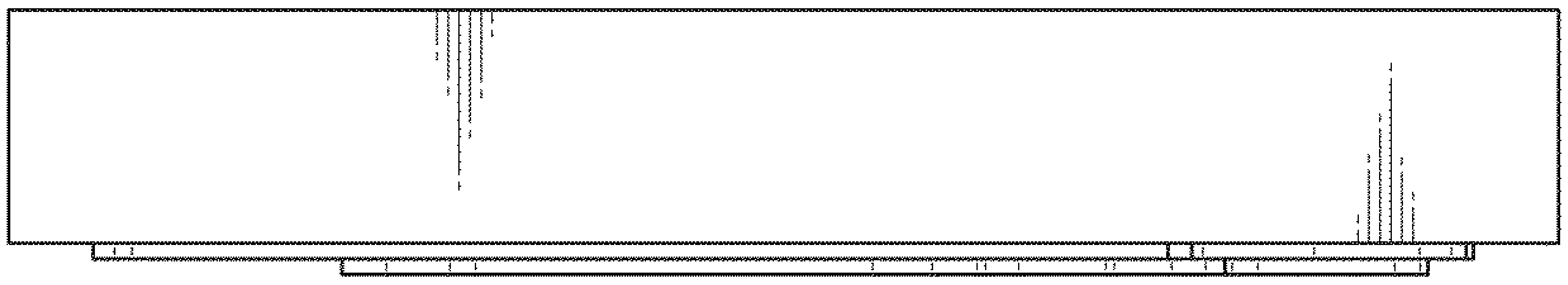

FIG. 10

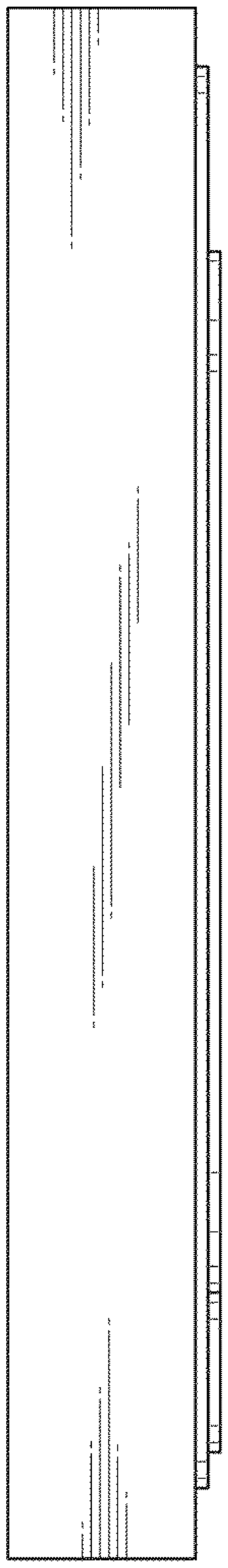

FIG. 11

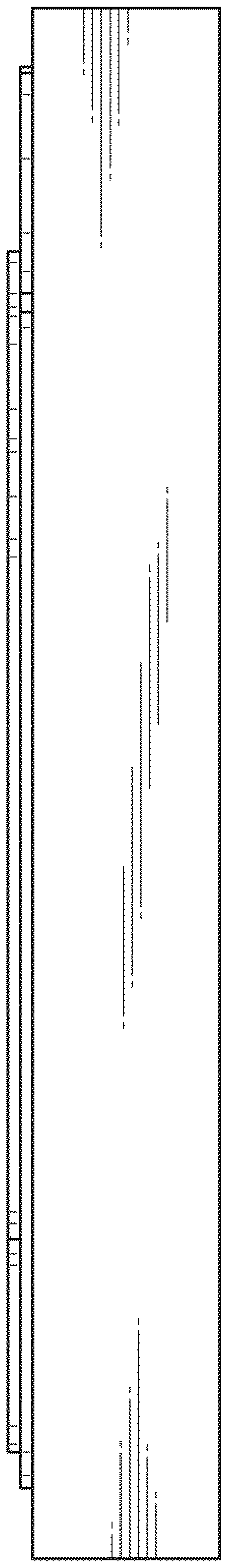

FIG. 12

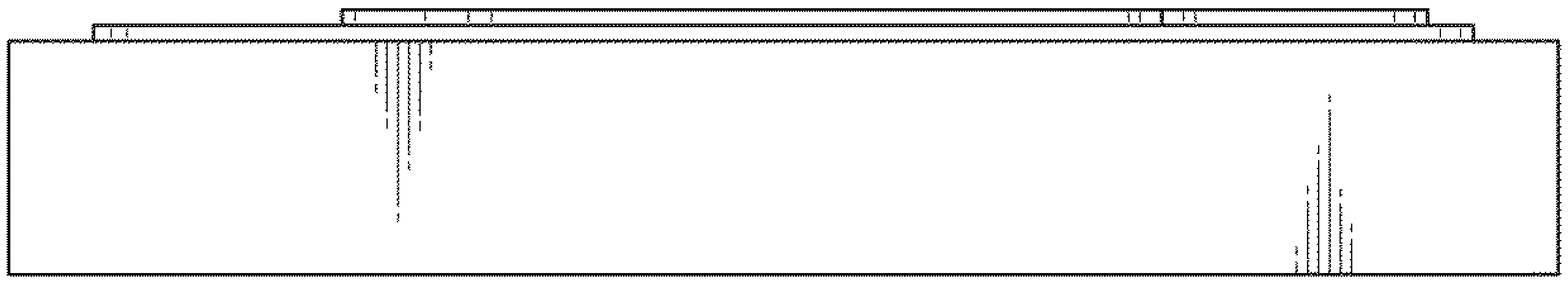

FIG. 13

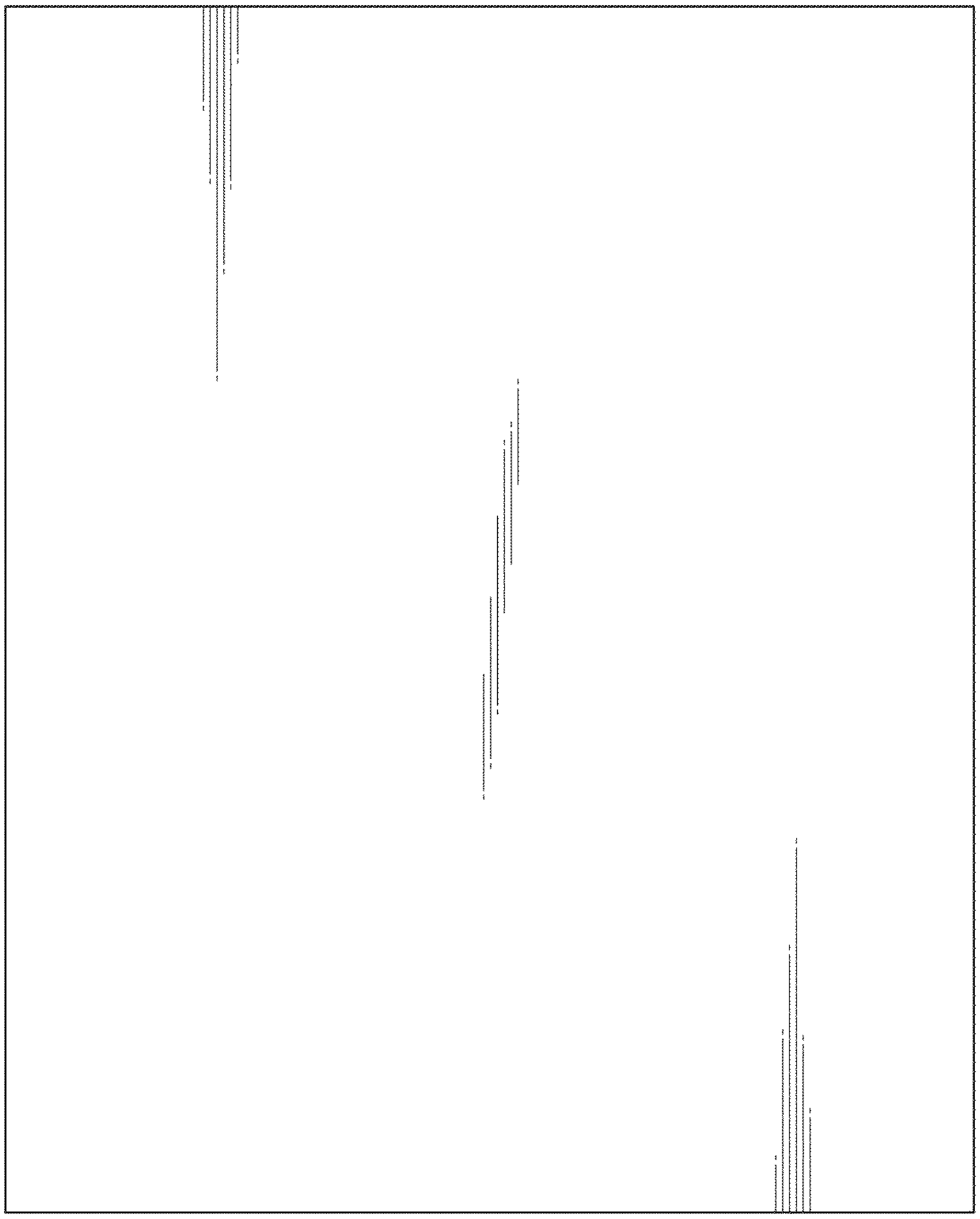

FIG. 14